

# 5A, 50V - 1000V Surface Mount Rectifier

#### **FEATURES**

- Glass passivated chip junction
- Ideal for automated placement
- Low forward voltage drop
- High current capability
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

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- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

#### **MECHANICAL DATA**

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Polarity: As marked
- Weight: 0.25 g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I <sub>F</sub>	5	Α		
$V_{RRM}$	50 - 1000	V		
I <sub>FSM</sub>	100	Α		
T <sub>J MAX</sub>	150 °C			
Package	(SMC)			









ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)									
PARAMETER	SYMBOL	S5 AC-K	S5 BC-K	S5 DC-K	S5 GC-K	S5 JC-K	S5 KC-K	S5 MC-K	UNIT
Marking code on the device		S5A	S5B	S5D	S5G	S5J	S5K	S5M	
Repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Reverse voltage, total rms value	V <sub>R(RMS)</sub>	35	70	140	280	420	560	700	V
Forward current	I <sub>F</sub>	5					Α		
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I <sub>FSM</sub>				100				А
Junction temperature	TJ	- 55 to +150				°C			
Storage temperature	T <sub>STG</sub>	- 55 to +150				°C			





THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP.	UNIT		
Junction-to-lead thermal resistance per diode	$R_{\Theta JL}$	11	°C/W		
Junction-to-ambient thermal resistance per diode	$R_{\Theta JA}$	48	°C/W		
Junction-to-case thermal resistance per diode	R <sub>eJC</sub>	12	°C/W		

Thermal Performance Note: Units mounted on PCB (16mm x 16mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	TYP.	MAX.	UNIT	
	I <sub>F</sub> = 2.5A, T <sub>J</sub> = 25°C		0.90	-	V	
Forward voltage per diode (1)	$I_F = 5.0A, T_J = 25^{\circ}C$	V <sub>F</sub>	0.96	1.15	V	
Forward voltage per diode	I <sub>F</sub> = 2.5A, T <sub>J</sub> = 125°C		0.78	-	V	
	I <sub>F</sub> = 5.0A, T <sub>J</sub> = 125°C		0.85	1.00	V	
Dayeres surrent @ reted // per diede (2)	T <sub>J</sub> = 25°C		-	10	μΑ	
Reverse current @ rated V <sub>R</sub> per diode <sup>(2)</sup>	T <sub>J</sub> = 125°C	l <sub>R</sub>	-	250	μΑ	
Junction capacitance	1 MHz, V <sub>R</sub> =4.0V	CJ	34	-	pF	

#### Notes:

- 1. Pulse test with PW=0.3 ms
- Pulse test with PW=30 ms

ORDERING CODE	PACKAGE	PACKING
S5AC-K R7G	SMC	850 / 7" Plastic reel
S5AC-K M6G	SMC	3,000 / 13" Plastic ree
S5BC-K R7G	SMC	850 / 7" Plastic reel
S5BC-K M6G	SMC	3,000 / 13" Plastic ree
S5DC-K R7G	SMC	850 / 7" Plastic reel
S5DC-K M6G	SMC	3,000 / 13" Plastic ree
S5GC-K R7G	SMC	850 / 7" Plastic reel
S5GC-K M6G	SMC	3,000 / 13" Plastic ree
S5JC-K R7G	SMC	850 / 7" Plastic reel
S5JC-K M6G	SMC	3,000 / 13" Plastic ree
S5KC-K R7G	SMC	850 / 7" Plastic reel
S5KC-K M6G	SMC	3,000 / 13" Plastic ree
S5MC-K R7G	SMC	850 / 7" Plastic reel
S5MC-K M6G	SMC	3,000 / 13" Plastic ree



#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.1 Forward Current Derating Curve

6 AVERAGE FORWARD CURRENT (A) 5 4 3 2 Heat sink 16mm x 16mm Cu pad test board 0 75 25 50 100 125 150 CASE TEMPERATURE (C)

Fig.2 Typical Junction Capacitance

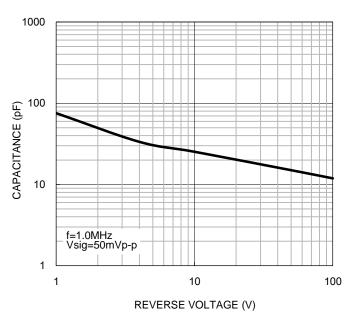
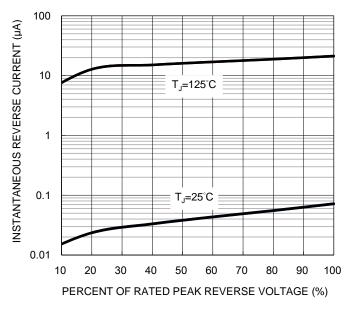
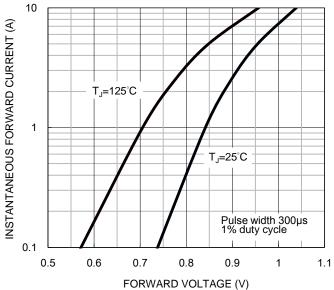


Fig.3 Typical Reverse Characteristics





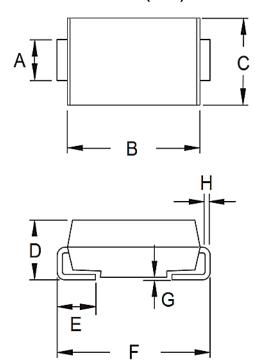


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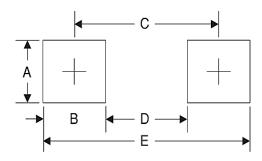
### **PACKAGE OUTLINE DIMENSIONS**

# DO-214AB (SMC)



DIM.	Unit	(mm)	Unit (inch)		
DIN.	Min	Max	Min	Max	
Α	2.90	3.20	0.114	0.126	
В	6.60	7.11	0.260	0.280	
С	5.59	6.22	0.220	0.245	
D	2.00	2.62	0.079	0.103	
Е	1.00	1.60	0.039	0.063	
F	7.75	8.13	0.305	0.320	
G	0.10	0.20	0.004	0.008	
Н	0.15	0.31	0.006	0.012	

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)	
А	3.30	0.130	
В	2.50	0.098	
С	6.80	0.268	
D	4.40	0.173	
E	9.40	0.370	

### **MARKING DIAGRAM**



P/N = Marking Code G =Green Compound

ΥW = Date Code F = Factory Code



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